

WHAT IS CLAIMED IS:

1. A circuit substrate comprising:

5 a first substrate on a first surface of which
circuit elements are loaded;
a second substrate on which the first substrate is
loaded; and

noise reduction elements each sandwiched between
an area of a second surface of the first substrate over
10 against the first surface of the first substrate and a
surface of the second substrate facing the second surface
of the first substrate, the noise reduction elements each
being connected between a power source terminal of the
second surface of the first substrate and a power source
15 terminal of the surface of the second substrate, and/or
between a ground terminal of the second surface of the
first substrate and a ground terminal of the surface of the
second substrate.

20 2. A circuit substrate according to claim 1,
wherein the noise reduction element is a chip condenser.

3. A circuit substrate according to claim 1,
wherein a signal terminal of the second surface of the
25 first substrate is connected with a signal terminal of the
surface of the second substrate in accordance with a ball
grid array system.

4. A circuit substrate according to claim 2,
wherein a signal terminal of the second surface of the
first substrate is connected with a signal terminal of the
5 surface of the second substrate in accordance with a ball
grid array system.

5. Electronic equipment on which a circuit
substrate is loaded, the electronic equipment being
10 operative in accordance with an electronic circuit
constructed on the circuit substrate, wherein the circuit
substrate comprises:

a first substrate on a first surface of which
circuit elements are loaded;

15 a second substrate on which the first substrate is
loaded; and

noise reduction elements each sandwiched between
an area of a second surface of the first substrate over
against the first surface of the first substrate and a
20 surface of the second substrate facing the second surface
of the first substrate, the noise reduction elements each
being connected between a power source terminal of the
second surface of the first substrate and a power source
terminal of the surface of the second substrate, and/or
25 between a ground terminal of the second surface of the
first substrate and a ground terminal of the surface of the
second substrate.

6. Electronic equipment according to claim 5,
wherein the noise reduction element is a chip condenser.

5 7. Electronic equipment according to claim 5,
wherein a signal terminal of the second surface of the
first substrate is connected with a signal terminal of the
surface of the second substrate in accordance with a ball
grid array system.

10 8. Electronic equipment according to claim 6,
wherein a signal terminal of the second surface of the
first substrate is connected with a signal terminal of the
surface of the second substrate in accordance with a ball
15 grid array system.